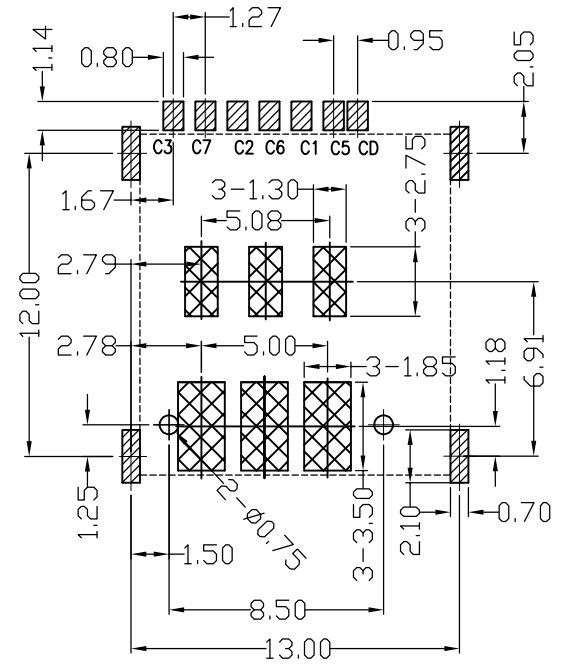
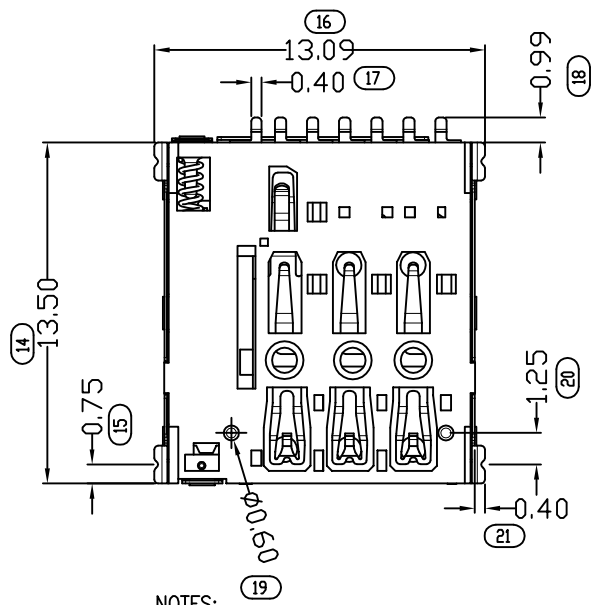
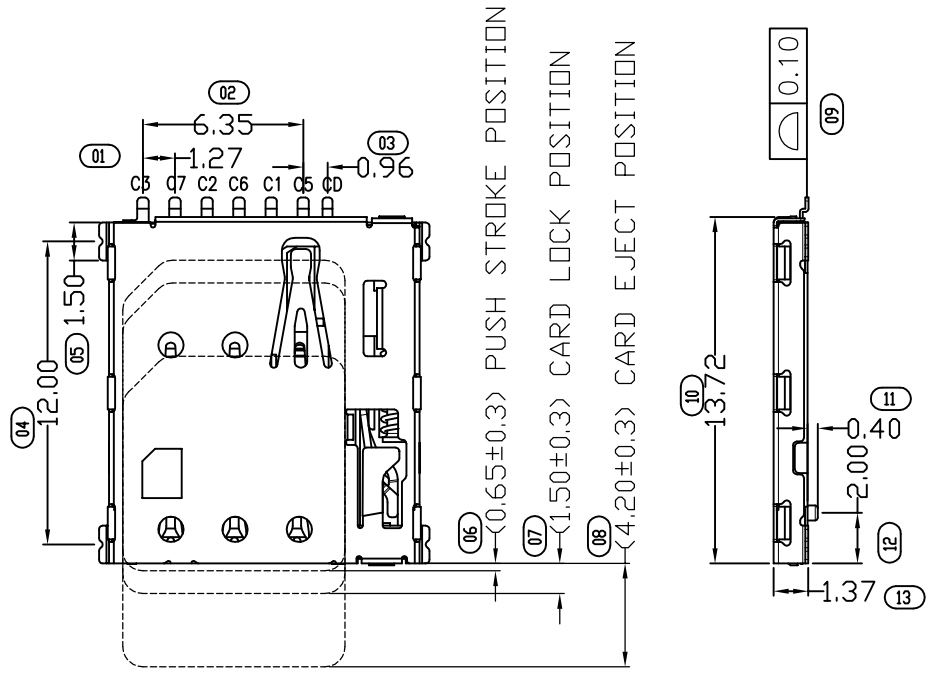
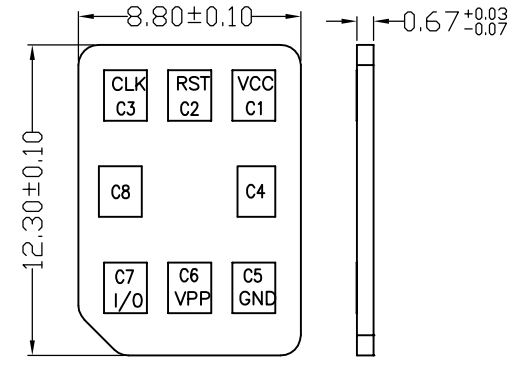
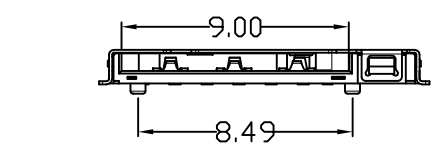


REV	NO	REVISION	DESCRIPTION	DATE
		NEW DWG		2016-03-12



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ?05



NANO SIM CARD

- NOTES:
- MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
CONTACT:COPPER ALLOY
SHELL:STAINLESS STEEL
 - PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
 - SPECIALITY:
3.1 Rated current:1.0A
3.2 Rated voltage:30V
3.3 Contact Resistance:100mΩ MAX
3.4 Insulation Resistance:1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability:260+0/-5°C, 30?0s.
3.7 Durability:5000 Cycles Min.
3.8 Operating condition:Temperature-40°C~-85°C;
Humidity 80% R.H MAX

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

		深圳市华德共创科技有限公司 Shenzhen Huade co-create Technology Co.,LTD 电话：0755-27111216 传真：0755-29940187			
		-TOLERANCES- UNLESS OTHERWISE SPECIFIED 公差参数表		TITLE: 产品名称: NANO 1.37H push 卡座	
X.X	±0.30	X.X*	±3*	APPD: 核准:	PART NO: 产品编号: K-DYX-010
X.XX	±0.20	X.XX*	±2*	CHECK: 校对: 王建业	
X.XXX	±0.10	X.XXX*	±1*	DRAW: 绘图: 黄艳兰	DATE
				2016-03-12	SCALE
				1:1	UNIT
				mm	CODE NUMB
					A001

